

Gap Filler 4000 (Two-Part)

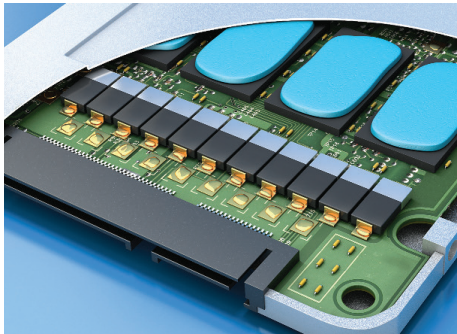
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PRODUCT DESCRIPTION

Thermally Conductive, Liquid Gap Filler Material

FEATURES AND BENEFITS

- Thermal Conductivity: 4.0 W/m-K
- Extended working time for manufacturing flexibility
- Ultra-conforming with excellent wet-out
- 100% solids - no cure by-products
- Excellent low and high temperature chemical and mechanical stability



Gap Filler 4000 is a two-part, high performance, thermally conductive, liquid gap filling material. The mixed material will cure at room temperature and can be accelerated with the addition of heat. Gap Filler 4000 offers an extended working time to allow greater flexibility in the customer's assembly process.

Liquid dispensed thermal materials offer infinite thickness variations and impart little to no stress on sensitive components during assembly. Gap Filler 4000 exhibits low level natural tack characteristics and is intended for use in applications where a strong structural bond is not required.

As cured, Gap Filler 4000 provides a soft, thermally conductive, form-in-place elastomer that is ideal for fragile assemblies or for filling unique and intricate air voids and gaps.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF GAP FILLER 4000

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color / Part A	Blue	Blue	Visual
Color / Part B	White	White	Visual
Viscosity, High Shear (Pa-s) (1)	50	50	ASTM D5099
Density (g/cc)	3.1	3.1	ASTM D792
Mix Ratio	1:1	1:1	—
Shelf Life @ 25°C (months)	5	5	—
PROPERTY AS CURED			
Color	Blue	Blue	Visual
Hardness (Shore 00) (2)	75	75	ASTM D2240
Heat Capacity (J/g-K)	0.8	0.8	ASTM D1269
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—
ELECTRICAL AS CURED			
Dielectric Strength (V/mil)	450	450	ASTM D149
Dielectric Constant (1000 Hz)	7.9	7.9	ASTM D150
Volume Resistivity (Ohm-meter)	10 ¹⁰	10 ¹⁰	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL AS CURED			
Thermal Conductivity (W/m-K)	4.0	4.0	ASTM D5470
CURE SCHEDULE			
Working Time @ 25°C (3)	240 min (4 hrs)	240 min (4 hrs)	-
Cure @ 25°C (hrs) (3)	24	24	-
Cure @ 100°C (min) (3)	30	30	-
1) Capillary Viscosity, 1500/sec, Part A and B measured separately. 2) Thirty second delay value Shore 00 hardness scale. 3) Parallel plate rheometer, see reactivity application note.			

TYPICAL APPLICATIONS INCLUDE

- Automotive electronics
- Computer and peripherals
- Between any heat-generating semiconductor and a heat sink
- Telecommunications

CONFIGURATIONS AVAILABLE

- Supplied in cartridge or kit form

Disclaimer

Note:

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